**ABSTRACT OF THE DISCLOSURE**

Provided are a material management apparatus and a material management method which are capable of efficiently managing an adequate amount of stock and order of materials used in a semiconductor manufacturing line. Specifically, an operation part (11) receives data (D3) from a data processing part (10), and receives data (D6) from an operation part (12). The data (D3) is data containing information of a material ID and information of the number of wafers to be processed in a first unit period of time. The data (D6) is data of an endurance limit number of material which is found by the operation part (12). The operation part (11) performs an operation of dividing the number of wafers to be processed by the endurance limit number, to find the number of material needed in processing all the wafers to be processed in the first unit period of time (i.e., an estimated number in use), and then outputs the result as data (D7). The data (D7) is inputted to an order management part (4).